



Advanced Technologies in 3D Nanofabrication

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Message from the Guest Editor

Dear Colleagues,

Complex 3D micro-/nanoarchitectures are receiving widespread attention due to their potential applications in metamaterials, bio-medical devices, robotics and micro-/nanoelectromechanical systems. While 2D patterns are now generally achievable through commercialized lithographic tools, sculpturing functional materials into 3D shapes and placing them at the desired locations in 3D spaces with high fidelity to designed layouts remain challenging. Several efforts have been made in this direction. To name a few, some have exploited the misfit strain and introduced shape transformation to turn originally 2D patterns into 3D configurations, while others extended the scope of conventional optical lithography and developed intricate optical systems to write photo-resist or functional materials directly into 3D structures. This Special Issue aims to collect research papers, short communications and review articles to present examples of the recent advance in 3D micro-/nano fabrication, with the emphasis on either technology development or application demonstration.

We look forward to receiving your submissions!

Prof. Dr. Mingliang Zhang
Guest Editor





Editor-in-Chief

Message from the Editor-in-Chief

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